

Product Change Notification

(Notification - P1602008-DIGI)

(CST-R2-T672)

March 15, 2016

To: *Our Valued Digi-Key, Inc. Customer*

Overview: The purpose of this notification is to communicate a product change for select Renesas Electronics America, Inc. (REA) devices. These devices have replacement part numbers.

This notification announces the change assembly and final test sites for certain 4Mb Low Power SRAM TSOP products. The table below describes the site changes.

	Current Site	New Site
Assembly Site	Amkor Technology Taiwan	Amkor Technology Malaysia
Final Test Site	Renesas Semiconductor Beijing	Powertech Technology Inc.

There are **no changes** to the wafer fabrication site, electrical characteristics (DC/AC), package materials, package dimensions, pin configurations, or product reliability & quality.

There are some changes to the packing specification. See the Appendix A for details.

Affected Products: The list of products below is affected by this notification.

Booking Part Number	Replacement Part Number
RMLV0408EGSA-4S2#AA0	RMLV0408EGSA-4S2#AA1
RMLV0408EGSA-4S2#KA0	RMLV0408EGSA-4S2#KA1

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Mass production shipments of the replacement part number begin from REA.	Jun. 15th, 2016
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Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

You are encouraged to sample the replacement device and begin qualification as soon as possible. Please contact you REA sales representative to obtain samples.

Please contact your REA sales representative for any questions or comments.

Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix A: RMLV0408EGSA-4S2 Comparison Table (32pin sTOSOP (I) package)

Item		Current	After	Remarks
Orderable part number		RMLV0408EGSA-4S2#AA0 (Tray packing) RMLV0408EGSA-4S2#KA0 (Tape & Reel packing)	RMLV0408EGSA-4S2#AA1 (Tray packing) RMLV0408EGSA-4S2#KA1 (Tape & Reel packing)	
Assembly Line		Amkor Technology Taiwan (Taiwan)	Amkor Technology Malaysia (Malaysia)	
Country of origin display		TAIWAN	MALAYSIA	
JEITA Package Code		P-TSOP(1)32-8x11.8-0.50	P-TSOP(1)32-8x11.8-0.50	compatible mounting
Package Marking Specification		<p>Country of origin (Back-End Line: Assembly)</p>	<p>Country of origin (Back-End Line: Assembly)</p>	
Material	Lead frame material	Cu	Cu	material is equivalent
	Lead frame pattern	Current specification	No change in specification	
	Lead plating	Pure Tin	Pure Tin	material is equivalent
	Die bonding	Epoxy paste	Epoxy paste	material is equivalent
	Wire bonding	Au	Au	material is equivalent
	Mold	Epoxy resin	Epoxy resin	material is equivalent
Final test Line		Renesas Semiconductor Beijing (China)	Powertech Technology Inc. (Taiwan)	
Tray packing	Packing Specification	Current specification	New specification	
	Tray	JEDEC Tray (TSOP I package size: 8mm x 11.8mm)	JEDEC Tray (TSOP I package size: 8mm x 11.8mm)	material is equivalent
	Storage number	234pcs/tray	234pcs/tray	
	Number of trays(Max.)	8 trays + 1 tray(cover)	10 trays + 1 tray(cover)	
Inner box size (LxWxH)		330mm x 152mm x 75mm	351mm x 175mm x 104mm	
Tape & Reel packing	Packing Specification	Current specification	New specification	
	Embossed tape	Current specification	New specification	No change in dimension
	Storage number	1,000pcs/reel	1,000pcs/reel	
	Inner box size (LxWxH)	288mm x 273mm x 48mm	340mm x 360mm x 60mm	
Shipping label		Current specification	No change in specification	Changes in orderable part name and country of origin